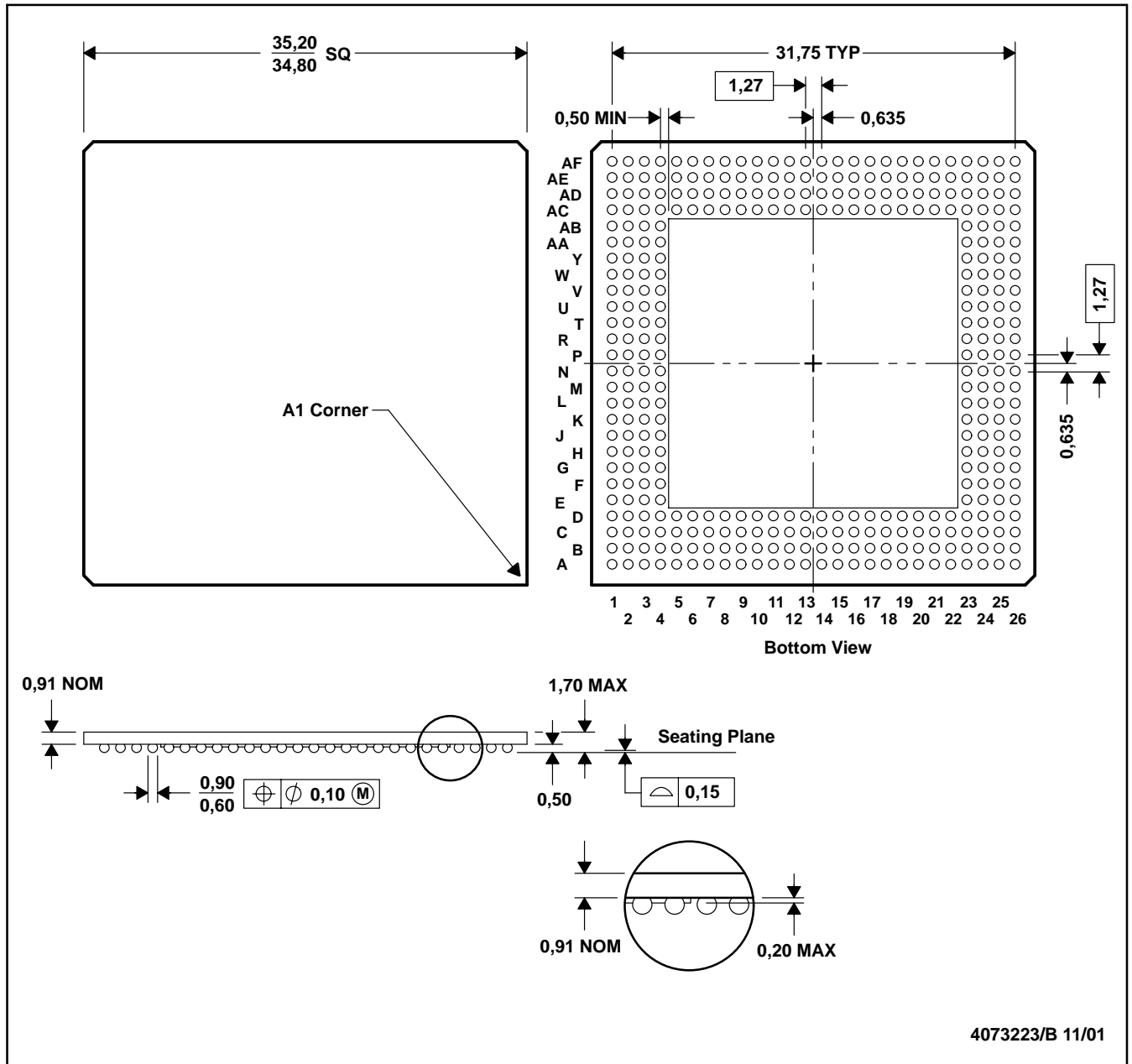


GGP (S-PBGA-N352)

PLASTIC BALL GRID ARRAY (CAVITY DOWN)



- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Thermally enhanced plastic package with metal heat slug (HSL)

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Mailing Address:

Texas Instruments
Post Office Box 655303
Dallas, Texas 75265